

Technical Data Sheet

MODEL NO: S282ANB4-5mA

0402Package 1.0*0.5mm Chip LEDs

Features :

•Package in 8mm tape on 7" diameter reel

•Compatible with automatic placement equipment

•Compatible with reflow solder process

Applications:

Indicators

•Automotive : backlighting in dashboard and switch

•Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	Blue	Water Clear

Electrical/Optical Characteristics(Ta=25°C)

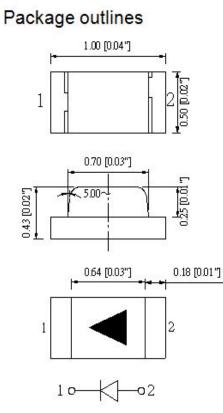
Parameter	Test Condition	Symbol	Value			- Unit
			Min	Тур	Max	Unit
Spectral half bandwidth	I⊧=5mA	$\bigtriangleup \lambda$		22		nm
Dominant wavelength	I⊧=5mA	λD	464		474	nm
Forward voltage	I⊧=5mA	VF	2.5		3.4	v
Luminous intensity	IF=5mA	lv	32	50	80	mcd
Viewing angle at 50% lv	IF=5mA	2 <i> </i>		120		Deg
Reverse current	Vr=5V	lr			10	μA



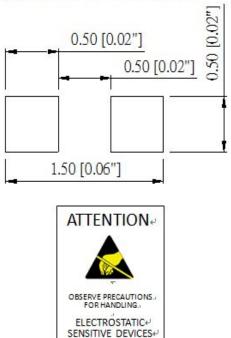
Absolute Maximum Ratings(Ta= 25° C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	108	mW
Forward current	lf	30	mA
Reverse voltage	Vr	5	V
Operating temperature range	Тор	-40 ~+80	°C
Storage temperature range	Tstg	-40 ~+85	°C
Peak pulsing current (1/8 duty f=1kHz)	IFP	125	mA

PACKAGING DIMENSIONS (mm):



Recommend Pad Layout

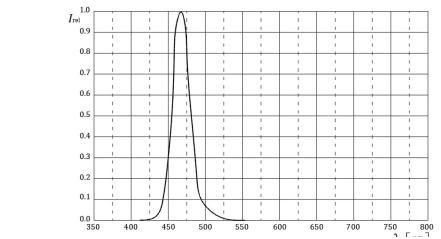




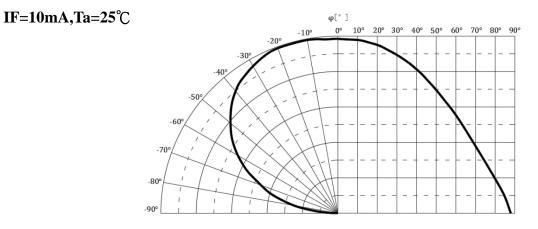
Typical Electro-Optical Characteristics Curve:

Relative Spectral Emission

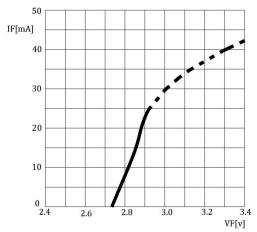
IF=5mA,Ta=25°C

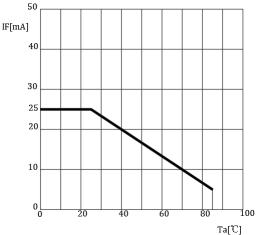


Radiation Characteristics



Forward Current vsForward Voltage Forward Current Derating Curve $Ta{=}25^\circ\!\mathbb{C}$







Precautions For Use :

Over - current - proof

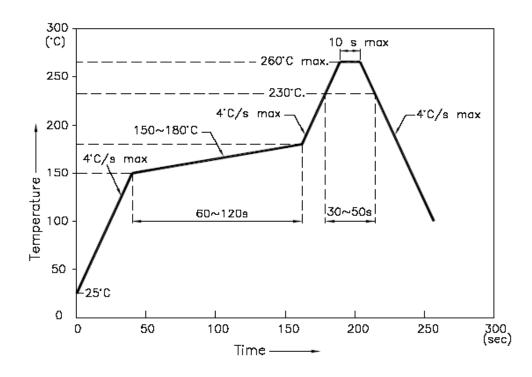
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

1. The operation of temperature and R.H. are $: 5^{\circ}$ C $\sim 30^{\circ}$ C, 60° R.H. Max.

- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}C\pm5^{\circ}C$ for 15 hrs.

■ Reflow Temp/Time



NOTES:

- 1. We recommend the reflow temperature $245^{\circ}C(\pm 5^{\circ}C)$.the maximum soldering temperature should be limited to $260^{\circ}C$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

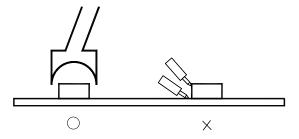


■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .

Rework

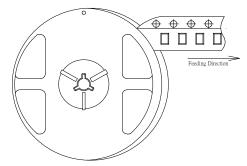
- 1. Customer must finish rework within 5 sec under 260° C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.

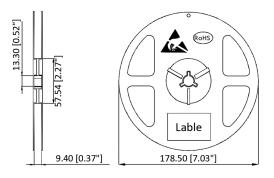


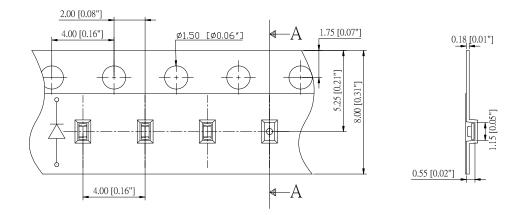
Feeding Direction

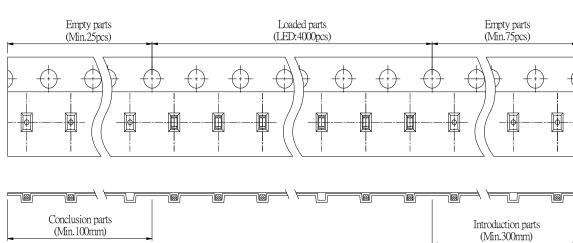


■Dimensions of Tape (Unit: mm)

Dimensions of Reel (Unit: mm)







■Arrangement of Tape

■Note

- 1. Empty component pockets are sealed with top cover tape;
- $\ensuremath{\mathbf{2}}.$ The maximum number of missing lamps is two.
- 3. 3,000 pcs/Reel.